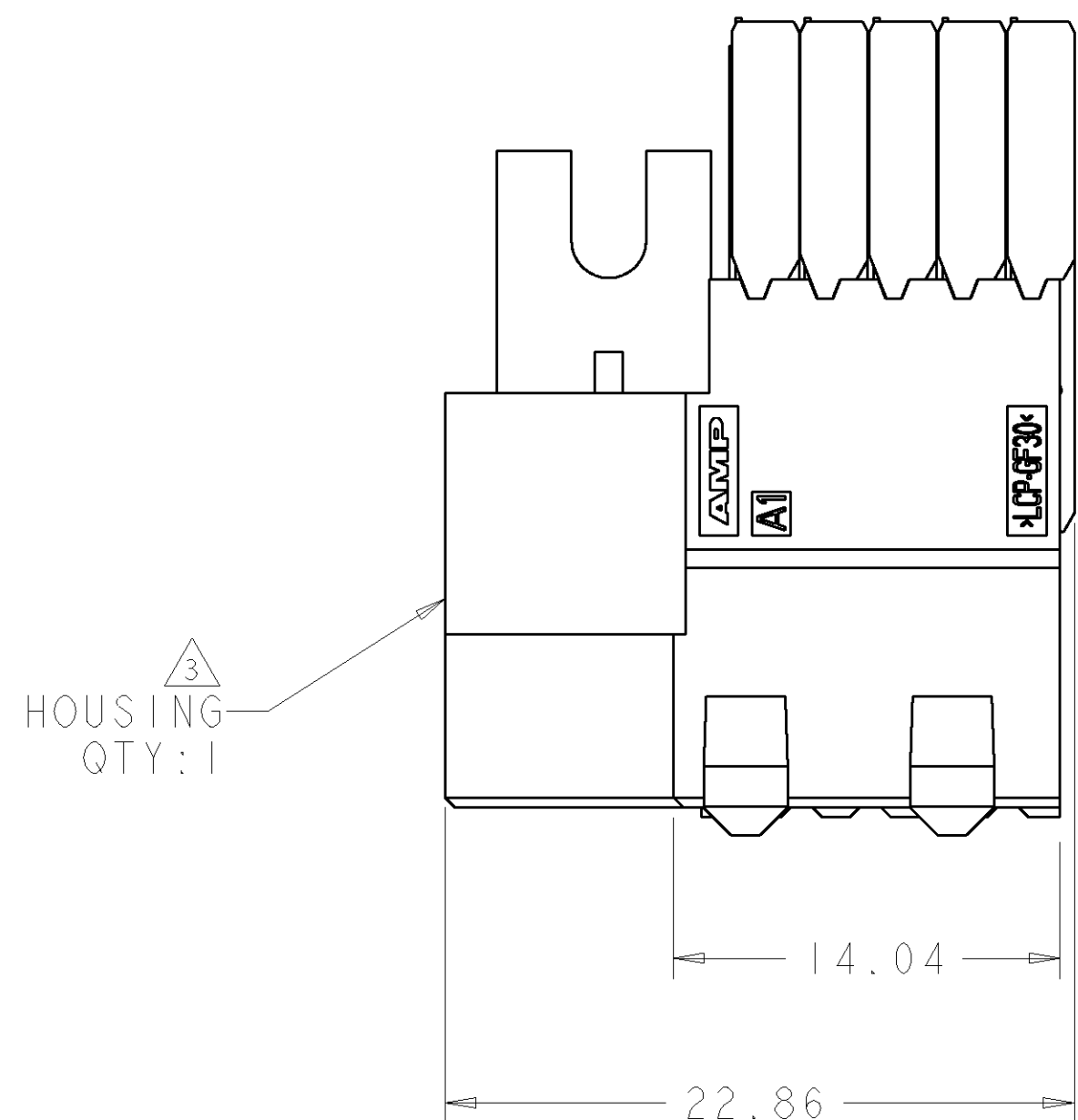
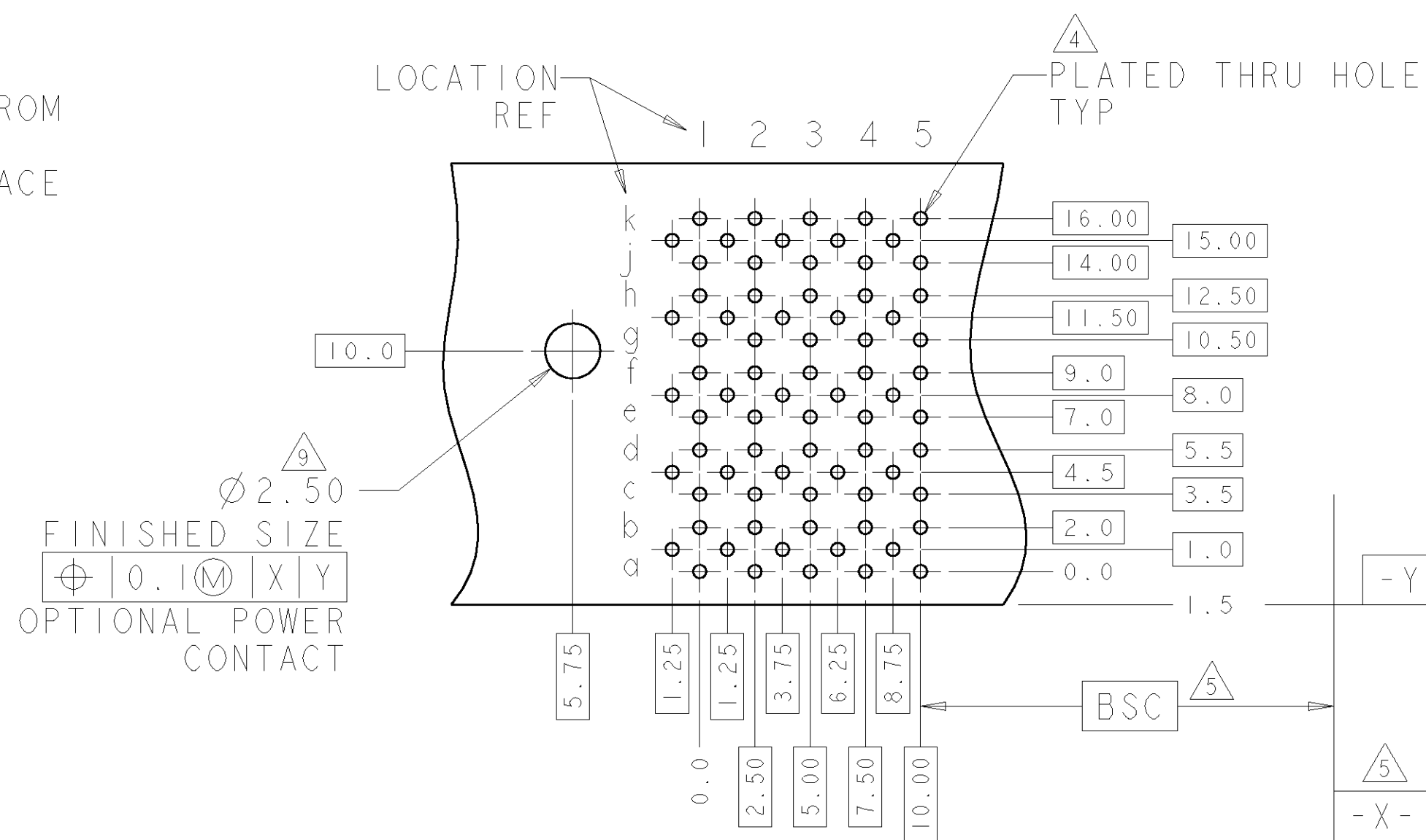
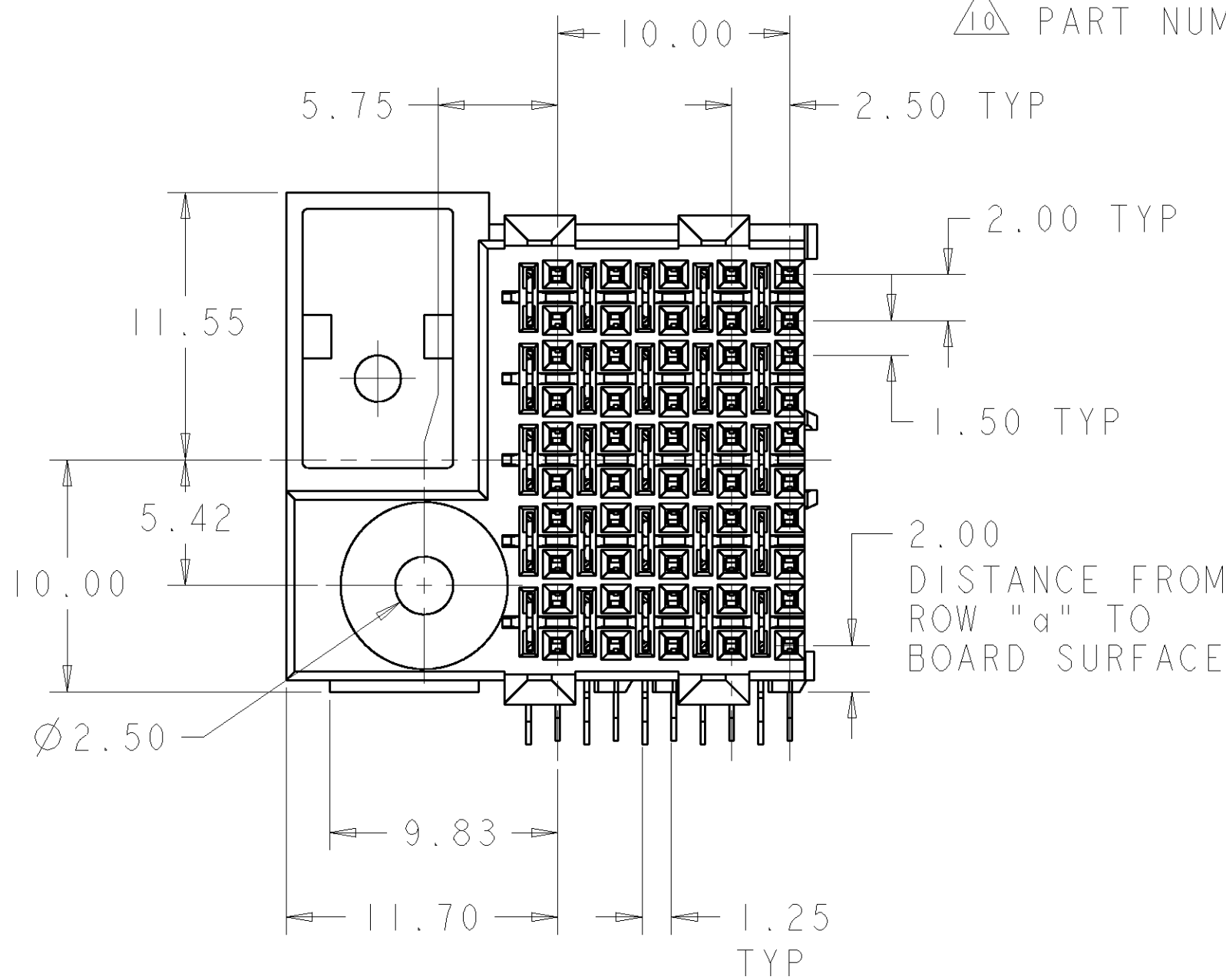




- △ 0.76μm MIN GOLD OVER 1.27μm MIN NICKEL UNDERPLATE OR GOLD
FLASH OVER 0.76μm MIN PALLADIUM-NICKEL OVER 1.27μm MIN NICKEL
UNDERPLATE ON CONTACT AREA
- △ 0.76μm MIN TIN OVER 1.27μm MIN NICKEL
- △ MATERIAL: CONTACT - COPPER ALLOY
SHIELD - PHOSPHOR BRONZE
HOUSING - LCP, UL94V-0
CHICKLET - GLASS FILLED POLYESTER
- △ REFERENCE APPLICATION SPEC 114-13020 FOR
RECOMMENDED PLATED THRU HOLE DIAMETER AND
PLATING THICKNESS.
- △ DATUM AND BASIC DIMENSION
ESTABLISHED BY CUSTOMER.
- △ SEATING HEIGHT TO BOARD SURFACE.
- △ CONTACT AREA LUBRICATED WITH BELLCORE
APROVED LUBRICANT. TECHNICAL REFERENCE:
GR-1217-CORE, ISSUE 1, NOVEMBER 1995.
- △ DATE CODE
- △ PART NUMBER



RECOMMENDED PRINTED
CIRCUIT BOARD LAYOUT
COMPONENT SIDE OF PRINTED CIRCUIT BOARD

